

TECHNICAL CHARACTERISTICS

1. General Characteristics

Dimension: 15.20L x 14.00W x 1.88H mm
 Weight: Approx. 0.45 g
 Contact principle: Friction technology
 Operating position: Shaft up / Down / Horizontal
 Mounting System: SMT Type (without post)
 Function: Push Push Type
 Durability: 5,000 cycles min.

2. Mechanical Characteristics

Insulation material: Thermoplastic, UL 94V-0
 RoHS Directive 2011/65/EU Compliant

3. Electrical Characteristics

Number of contacts: 8 pins
 Contact resistance: 100 mΩ / 20 mA
 Insulation resistance: >1000 MΩ / 500 VDC

4. Solderability

Wave: Not applicable
 IR reflow: 260°C, 10 sec. Max.
 Manual soldering: 360°C, 3 sec. Max.

5. Environmental Characteristics

Operating temperature: - 25°C ~ + 85°C
 Operating humidity: 10 % ~ 95 % RH
 Storage temperature: - 40°C ~ + 85°C
 Storage humidity: 10 % ~ 95 % RH

6. Pin Assignments

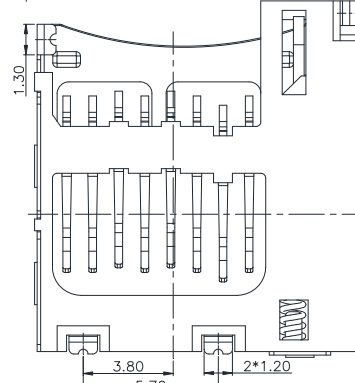
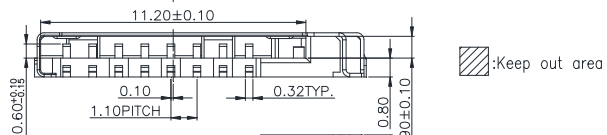
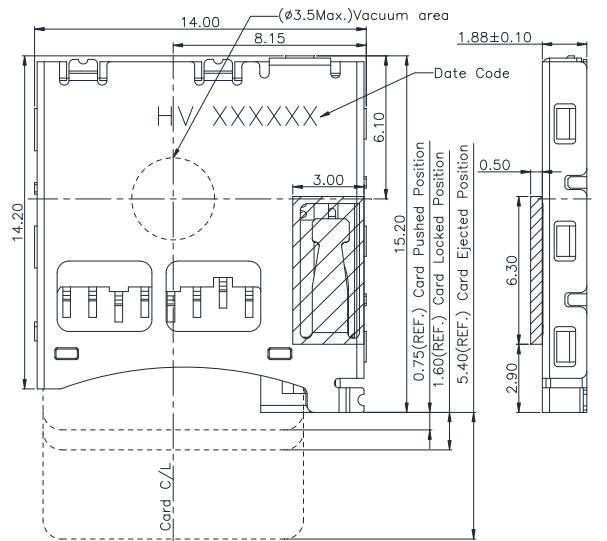
Pin	Micro SD Mode	
	Name	Description
1	DAT2	Data Line (Bit 2)
2	CD/DAT3	Card Detect / Data Line (Bit 3)
3	CMD	Command Response
4	VDD	Supply Voltage
5	CLK	Clock
6	VSS	Supply Voltage Ground
7	DAT0	Data Line (Bit 0)
8	DAT1	Data Line (Bit 1)

H&V Micro SD Card Connector

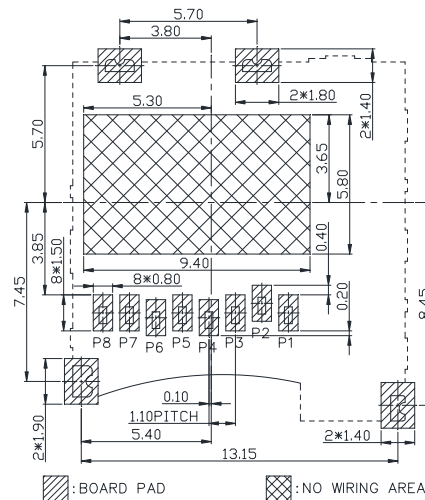
Model No.: MCA-T02

Revision: 2.0

Date: MAY 01, 2014



Unit: mm; Tolerances: ±0.15 mm
Mechanical outline dimension



Unit: mm; Tolerances: ±0.05 mm
Reference dimension for PCB layout

Note:

1. Coplanarity of solder pins 0.10mm max.
2. Recommended thickness of solder paste > 0.15mm.